

L Number	Hits	Search Text	DB	Time stamp
1	0	("9755282").PN.	USPAT	2004/09/26 12:08
2	1	("6191023").PN.	USPAT	2004/09/26 12:24
3	1	("5923088").PN.	USPAT	2004/09/26 12:27
4	100	((bond adj pad\$1) with ((insulation or dielectric or passivation or passivating) and barrier)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:30
5	7	((bond adj pad\$1) with ((insulation or dielectric or passivation or passivating) and barrier)) and (@ad<19991118)) and ((tan or (tantalum adj nitride)) with barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:39
6	0	(boand adj pad) and ((tan or (tantalum adj nitride)) with barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:33
7	51	(bond adj pad) and ((tan or (tantalum adj nitride)) with barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:33
8	16	((bond adj pad) and ((tan or (tantalum adj nitride)) with barrier)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:08
9	550	pad and ((tan or (tantalum adj nitride)) with barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:40
10	723	(pad and ((tan or (tantalum adj nitride)) with barrier)) (pad with (tan or (tantalum adj nitride)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:42
11	54	(pad and ((tan or (tantalum adj nitride)) with barrier)) and (pad with (tan or (tantalum adj nitride)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 12:42
12	13	((pad and ((tan or (tantalum adj nitride)) with barrier)) and (pad with (tan or (tantalum adj nitride)))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:40
13	15	438/612.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:18
14	249	438/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:22
15	46	(438/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)) and ((bond or solder or wire) with pad)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:22
16	383	257/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:25
17	97	(257/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)) and ((bond or solder or wire) with pad)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:22
18	57	((257/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)) and ((bond or solder or wire) with pad)) not ((438/\$.cccls. and pad and ((tan or (tantalum adj nitride)) and (@ad<19991118)) and ((bond or solder or wire) with pad)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:23

19	4	257/779.ccls. and pad and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:25
20	0	228/120.ccls. and pad and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:26
21	4253	pad and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:26
22	20	174/\$.ccls. and pad and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:27
23	22	((matrix or reinforced or thick) near pad) and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:29
24	0	(plurality near pad@1) and ((tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:29
25	469	(bond adj pad\$1) and ((insulation or dielectric or passivation or passivating) with (vias or hole)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:32
26	745	(bond adj pad\$1) and ((insulation or dielectric or passivation or passivating) with (vias or hole or recess or openings)) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:33
27	50	((bond adj pad\$1) and ((insulation or dielectric or passivation or passivating) with (vias or hole or recess or openings)) and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (vias or hole or recess or openings))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:45
28	254	257/E23.015.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:46
29	4	(257/E23.015.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (vias or hole or recess or openings))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:46
30	457	257/E23.037.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:47
31	0	(257/E23.037.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (vias or hole or recess or openings))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:41
32	9	(257/E23.037.ccls. and (@ad<19991118)) and (barrier or tan or (tantalum adj nitride))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:41
33	52	257/E23.038.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:57
34	10	(257/E23.038.ccls. and (@ad<19991118)) and (barrier or tan or (tantalum adj nitride))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:50
35	107	257/459.ccls. and (barrier or tan or (tantalum adj nitride))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:57

36	89	(257/459.ccls. and (barrier or tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:57
37	609	257/E23.02.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:57
38	137	(257/E23.02.ccls. and (@ad<19991118)) and (barrier or tan or (tantalum adj nitride))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 13:57
39	137	((257/E23.02.ccls. and (@ad<19991118)) and (barrier or tan or (tantalum adj nitride))) and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:41
40	2	6362528.URPN.	USPAT	2004/09/26 14:13
41	0	6710460.URPN.	USPAT	2004/09/26 14:14
42	0	6710460.URPN.	USPAT	2004/09/26 14:14
43	10	("5016087"   "5172212"   "6180505"   "6191023"   "6198170"   "6362528"   "6376353"   "6399477"   "6555459"   "6559545"   "2002/0146901").PN.	USPAT	2004/09/26 14:14
44	6	6306749.URPN.	USPAT	2004/09/26 14:16
45	26	5751065.URPN.	USPAT	2004/09/26 14:30
46	0	257/758.ccls, and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:41
47	1547	257/758.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:55
48	147	(257/758.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (trench or vias or hole or recess or openings))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:55
49	54	((257/758.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (trench or vias or hole or recess or openings))) and pad\$1	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:49
50	93	((257/758.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (trench or vias or hole or recess or openings))) not (((257/758.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (trench or vias or hole or recess or openings))) and pad\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:49
51	1536	438/612.ccls. and (@ad<19991118)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:55
52	26	(438/612.ccls. and (@ad<19991118)) and ((barrier or tan or (tantalum adj nitride)) with (trench or vias or hole or recess or openings))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/09/26 14:55